



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-03-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STCS05DR	ZPO7*UM64J51	A	SHENZHEN B/E	2016-03-21
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAuAg	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.9-6-1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ZP07*UM64J51					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.417	mg	supplier	die	Silicon (Si)	7440-21-3		2.248	mg	930079	28100
				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	9516	288
				supplier	metallization	Tungsten (W)	7440-33-7		0.024	mg	9930	300
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	827	25
				supplier	Passivation	Silicon Oxide	7631-86-9		0.101	mg	41787	1263
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	414	13
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	827	25
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.004	mg	1655	50
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.012	mg	4965	150
				Leadframe	Copper & Its alloys	32.000	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.015	mg	469	188
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.027	mg	844	338
supplier	metallization	Nickel (Ni)	7440-02-0						0.044	mg	1375	550
supplier	metallization	Palladium (Pd)	7440-05-3						0.001	mg	31	13
supplier	metallization	Gold (Au)	7440-57-5						0.001	mg	31	13
supplier	metallization	Silver (Ag)	7440-22-4						0.001	mg	31	13
supplier	glue or tape	Silver (Ag)	7440-22-4						0.407	mg	910515	5088
Die attach	Other Organic Materials	0.447	mg	supplier	glue or tape	acrylate	Proprietary		0.022	mg	49217	275
				supplier	glue or tape	Methacrylate	Proprietary		0.018	mg	40268	225
				supplier	wire	Gold (Au)	7440-57-5		0.143	mg	1000000	1788
Bonding wires	Other inorganic materials	0.143	mg	supplier	wire	Gold (Au)	7440-57-5		0.143	mg	1000000	1788
				supplier	mold compound	Silica, vitreous	60676-86-0		38.964	mg	866001	487050
Encapsulation	Other Organic Materials	44.993	mg	supplier	mold compound	Epoxy Resin	25068-38-6		3.374	mg	74989	42175
				supplier	mold compound	Phenol Resin	29690-82-2		2.250	mg	50008	28125
				supplier	mold compound	Carbon black	1333-86-4		0.225	mg	5001	2813
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.180	mg	4001	2250